

Spring Probe WLCSP Probe Head CCC – ISMI Characterization Is Not Enough

Valts Treibergs Research & Development Engineering Manager valts.treibergs@cohu.com

Abstract:

A recognized standard for evaluating the CCC (current carrying capacity) of an interconnect used at wafer probe has been the ISMI Probe Council Current Carrying Capability Measurement Guideline, published by International SEMATECH Manufacturing Initiative in 2009. The ISMI test is a relatively simple way to observe the interconnect force degradation as a function of current applied. The guideline evaluates at what point the contact sees a 20% force reduction. This 20% force reduction, means that the contact has been permanently deformed, and this is therefore a truly destructive test.

The ISMI guideline has been used to measure the CCC of spring probes for several years, and it does provide a value that can be used to compare one technology to another. The resulting value, however, does not describe the CCC for the actual test application. It will be shown that in controlled laboratory experiments, probes run at or near the ISMI CCC values in simulated test environments prematurely fail by taking a permanent set. Data from several configurations and probe types will be shown that behave in this manner.

12367 Crosthwaite Circle Poway, CA 92064-6817 Phone: (858) 848-8100 Fax: (858) 848-8185 www.cohu.com

























			Final Force		Force Difference (final-start)
Probe	Current (mA)	F.L. (mm)	Avg F (g)	F Std (g)	Percentage
1	10	4.300	7.747	0.701	0%
2	10	4.296	7.532	1.001	4%
3	400	4.284	7.478	0.737	-3%
4	400	4.288	6.230	0.490	-10%
5	600	4.278	7.059	0.947	7%
6	600	4.280	6.440	0.514	2%
	860	4.252	4.535	0.18/	-36%
8	860	4.256	4.155	0.167	-44%
9	1000	4.232	4.044	0.294	-47%
10	1000	4.128	0.027	0.001	-117%

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- ISMI predicted 20% force reduction did not correlate to probe CCC during cycling
- Rapid drop-off after 700 mA

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Wrap-Up

- Advance qualification testing, such as the METS Test as used and proposed by TI appears to be the best tool to predict the lifetime of spring pin contact interfaces
- Further industry cooperation and standardization on this method is warranted, although every interface has unique requirements, thus needs to be applied properly



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